

SOT617-3

DFN5050-32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

8 June 2016 **Package information**

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package type industry code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002

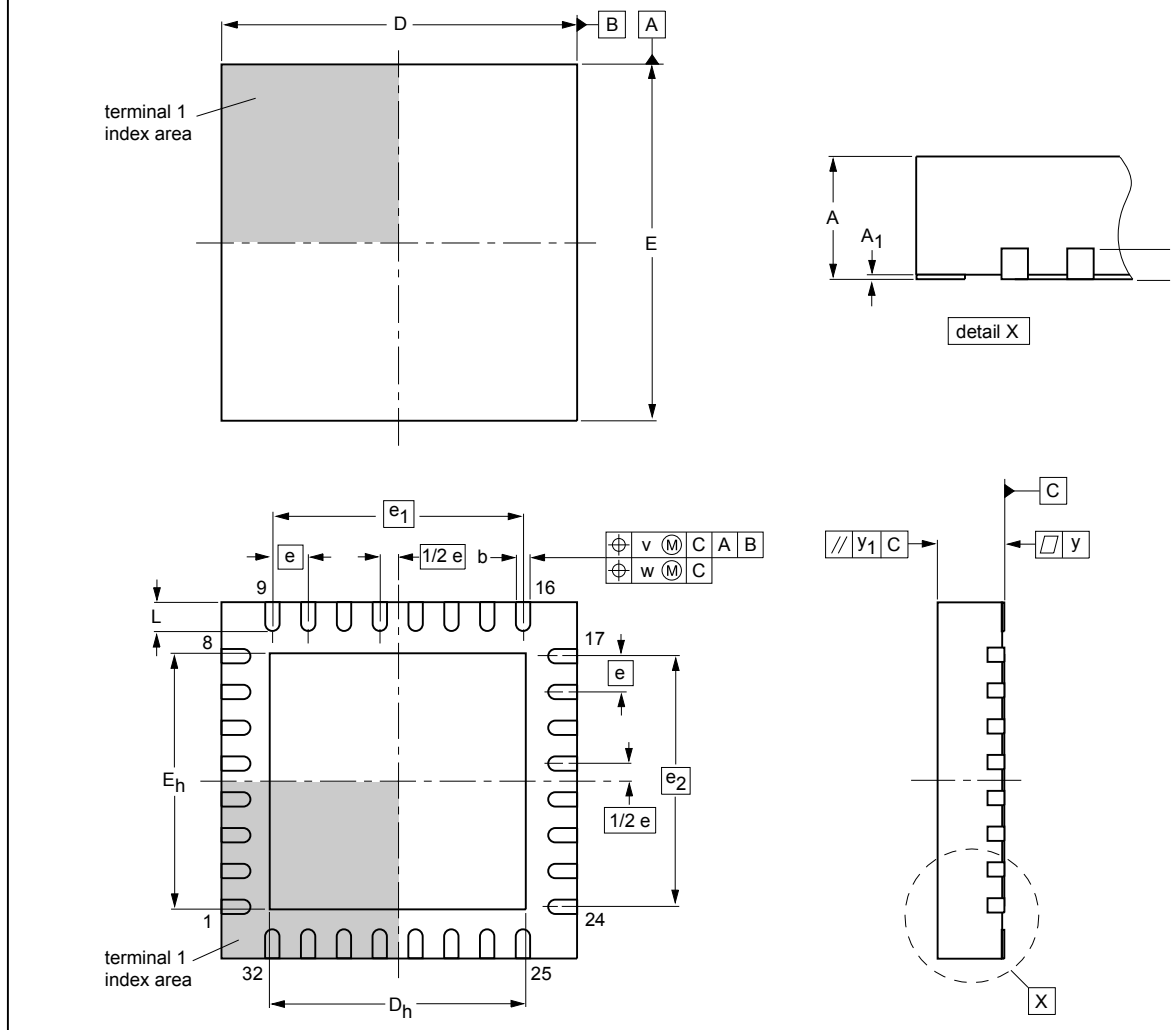
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		4.9	-	5	5.1	mm
A	seated height		-	-	0.85	-	mm
A_2	package height		-	-	-	-	
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	32	-	

DFN5050-32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

2. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm **SOT617-3**



Dimensions

Unit[1]		A[1]	A_1	b	c	D[1]	D_h	E[1]	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	max	0.85	0.05	0.30	0.2	5.1	3.75	5.1	3.75	0.5	3.5	3.5	0.5	0.1	0.05	0.05	0.1
	nom																
	min		0.00	0.18		4.9	3.45	4.9	3.45				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT617-3		MO-220				~~11-06-14~~ 11-06-21

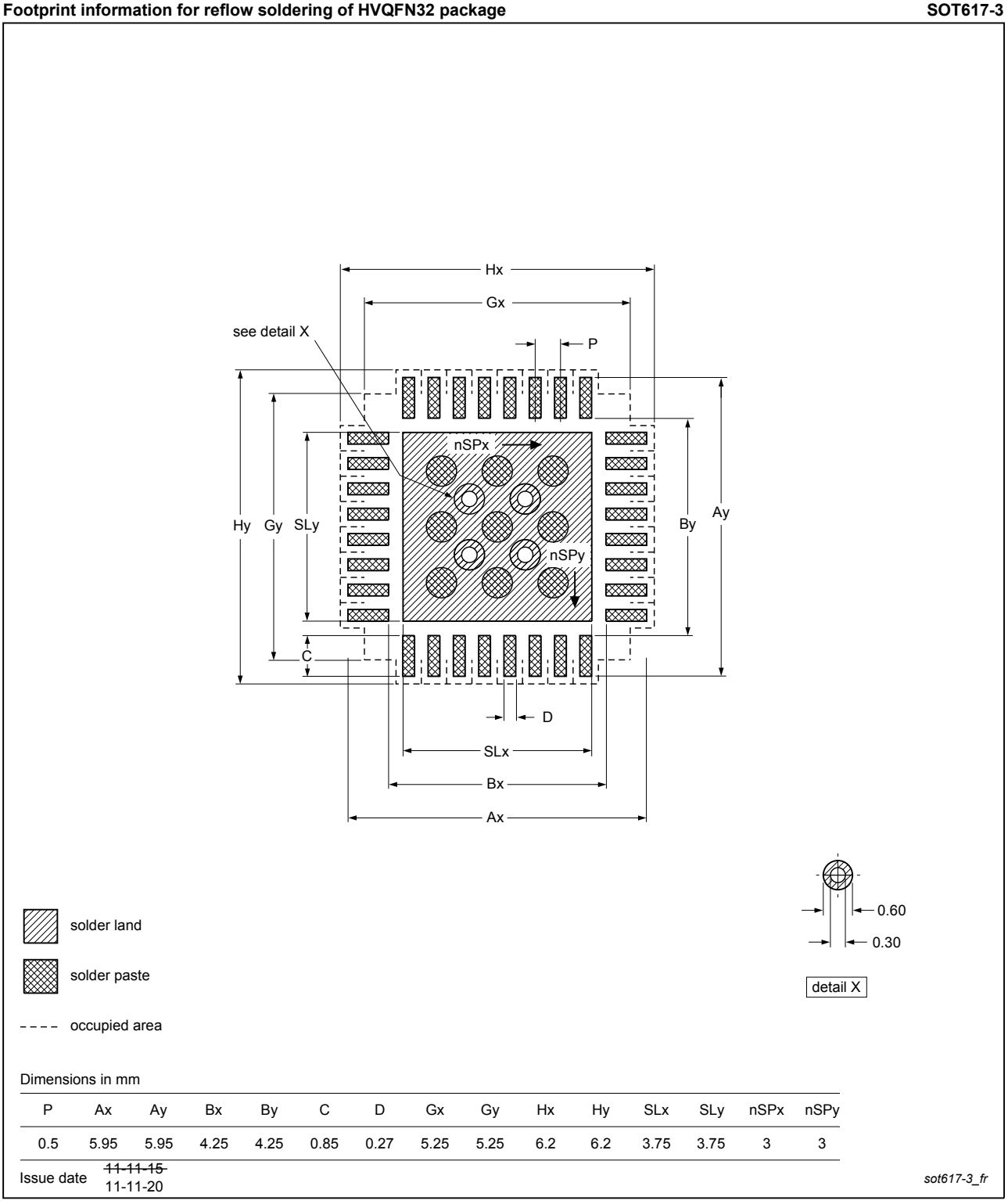
Fig. 1. Package outline HVQFN32 (SOT617-3)

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3. Soldering

Footprint information for reflow soldering of HVQFN32 package **SOT617-3**



Dimensions in mm

P	Ax	Ay	Bx	By	C	D	Gx	Gy	Hx	Hy	SLx	SLy	nSPx	nSPy
0.5	5.95	5.95	4.25	4.25	0.85	0.27	5.25	5.25	6.2	6.2	3.75	3.75	3	3

Issue date ~~11-11-15~~ 11-11-20

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Fig. 2. Reflow soldering footprint for HVQFN32 (SOT617-3)

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